



**PYRAMID**  
PACKAGING INC

## APStat™ Static Dissipative Film (APST)

The APStat product line is designed for the packaging of non-ESD static-sensitive electrical and electronic components. APStat material is designed to dissipate static build-up on the bag, thereby protecting the packaged product against a static discharge.

This linear low density polyethylene is amine free and polycarbonate and silver solder compatible. APStat is available in clear (APST), pink (APSP), blue (APSB), clear-white (CWAP) and blue-white (BWAP).

Genuine Autobag® bags-on-a-roll are system-matched and guaranteed to run on all Automated Packaging Systems' bagging equipment.

### Technical Information

Press Printing	Yes
Imprinting	Yes
Trim Seal	Yes
Mil Thickness	1.5, 2.0, 3.0
Configuration	Autobag; SidePouch and AirPouch with restrictions
Static Charge Dissipation	5000v to <50v, <2.0 sec
Surface Resistivity	>1 x 10 <sup>5</sup> <1 x 10 <sup>12</sup> Ohms/in <sup>2</sup>

Performance Data:	U/M	1.5/LD	2.0/SD	3.0/ET	ASTM
Haze	%	15.6	13.7	16.5	D-1003
Puncture Resistance (Dart)	grams	170	230	315	D-1709
Tensile Strength MD	psi	3423	3518	3604	D-882A
Tensile Strength TD	psi	2687	2665	3099	D-882A
Elongation MD	%	489	555	670	D-882A
Elongation TD	%	654	619	754	D-882A
Elmendorf Tear MD	grams	197	385	788	D-1922
Elmendorf Tear TD	grams	920	1190	1662	D-1922
OTR	cc/100in <sup>2</sup> /day	157.9	118	92	D-3985
MVTR	g/100in <sup>2</sup> /day	.48	.43	.31	F-1249

### Formulations

- APST
- APSP
- APSB
- CWAP
- BWAP



### Features & Benefits

- Amine Free
- Polycarbonate & Silver Solder Compatible



Chart reflects nominal test data values. Actual results may fluctuate due to inherent process variation. Test data and mil thickness reflect APST material only. Certain minimum purchase volumes may apply.